

Circuitry Paste

Applicable to display and mobile device circuitry

Applications

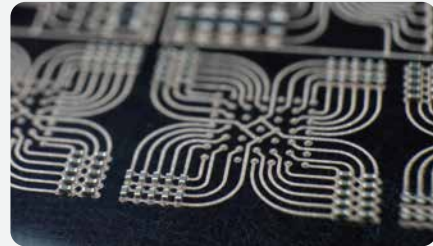
Printed Circuitry and antenna

Widely applicable (e.g.: Heater application)

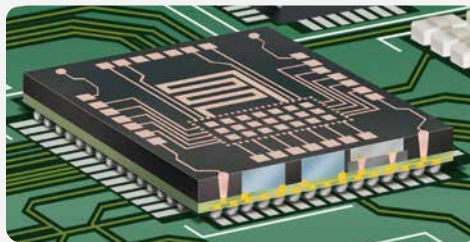
Circuitry for LED chips



Circuitry on glass substrates



Printed antenna on semiconductor packages



Features

- Excellent adhesion to low heat resistance substrates PET, COP and PEN
- Printed metal seed layer for plating
- Fine pattern (L/S= 75/75 μ m)

Product line-up & properties

Product			SW180	SW180T7	SW601
Type			Fine patterning	Thin layer	Bendable
Viscosity	BH type	dPa·s	1,300 - 1,700	1,000 - 1,400	
Volume resistivity (Representative value)	Curing(drying) conditions	$\Omega \cdot \text{cm}$	8.0E-05	6.0E-05	5.0E-05

